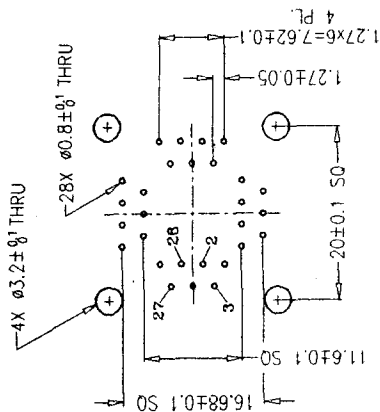
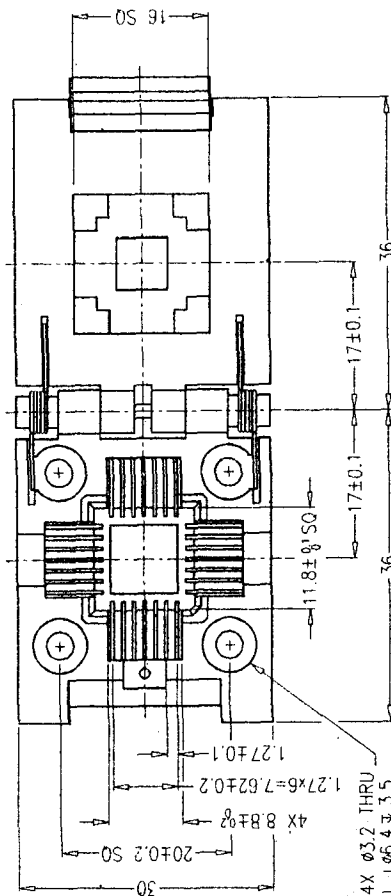
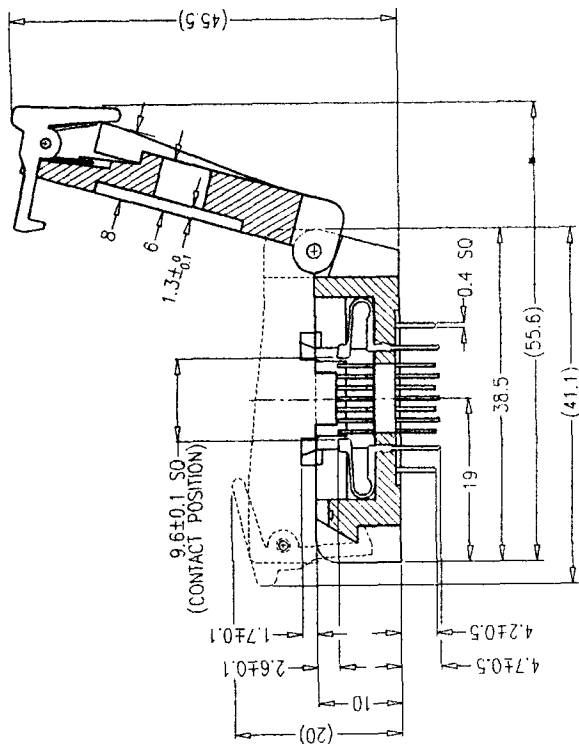
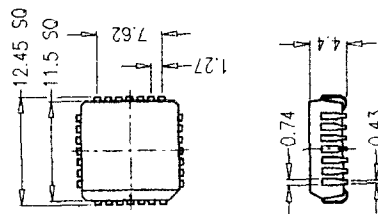


PC BOARD PATTERN (TOP VIEW)



• Denoted pin#1 location



SPECIFICATIONS:

Materials

Insulator Material: Glass Filled Polyether-sulphone, UL94V-0
 Contact Material: Beryllium Copper
 Contact Finish: 10µ" Gold Over Nickel Or NiB Over Nickel
 Operating Temp: -55°C~ +170°C

JEDEC PACKAGE: MS-018AF

Electrical Performance

Contact Resistance: 30mΩ, Max. Initial
 Insulation Resistance: 1000MΩ, Min.
 Dielectric Strength: 700V AC Continuous For 1 Minute
 Inductance (Self): 8.9 nH Max. At 100 MHz
 8.8 nH Max. At 200 MHz

DATE: 08/02/99

ISSUE: 1

PART NO: 180-7723

DRAWN: W. BERRY

DIMENSIONS: mm

WINSLOW ADAPTICS
 BRECON ENTERPRISE PARK
 BRECON
 POWYS
 LD3 8EF